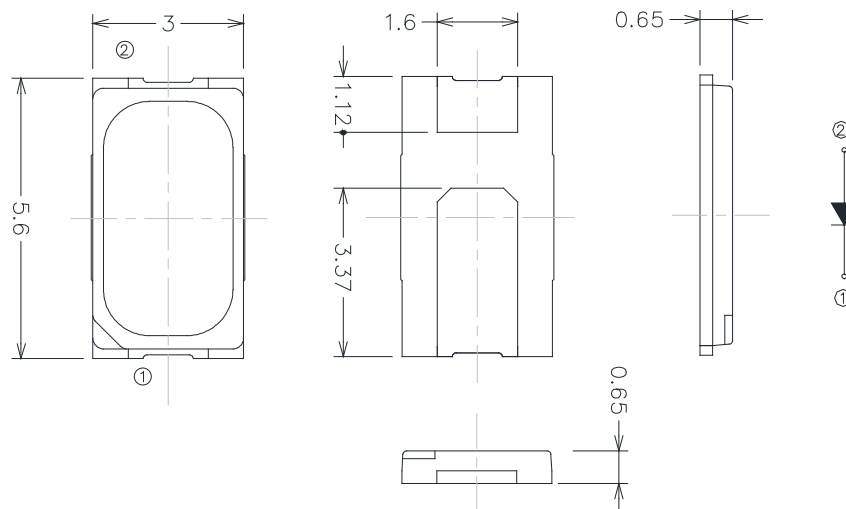


Features

- 5.6mm*3.0mm SMT LED, Super thin (0.65H mm)
- Wide Viewing Angle
- Various Colors
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow and wave solder process.
- Meet ROHS Green Product

Applications

- Backlight and Indicator

Package Dimensions**Notes:**

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2\text{mm}$ (.0079") unless otherwise noted.
3. Specifications are subject to change without notice



Selection Guide

Part No	Lens Type	Dice	Emitted Color
FSL-5630065W-FAT15N4065SBD	Yellow	InGaN	White

Electrical / Optical Characteristics At Ta=25 °C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Φ_v	Luminous Flux	30.0	48.0	65.0	Lm	IF=120mA
2 θ 1/2	Viewing Angle		120		deg	
Tc	Color Temperature	2550	5700	7000	K	IF=120mA
Ra	Color Rendering Index	70				IF=120mA
VF	Forward Voltage	2.7	3.0	3.5	V	IF=120mA
IR	Reverse Current			50	μ A	VR=5V

Note:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 optical centerline value

Absolute Maximum Ratings At Ta=25°C

Parameter	White	Unit
Power Dissipation	350	mW
Peak Forward Current(duty 1/10@10ms)	300	mA
Continuous Forward Current (each dice)	200	mA
Dreading Linear From25°C	0.25	mA/°C
Reverse Voltage(each dice)	5	V
Thermal Resistance (Junction/Soldering point)	21	° C/W
Junction Temperature	115	° C
Electrostatic Discharge Threshold(HBM)	2000	V
Operating Temperature Range	-40°C to + 85°C	
Storage Temperature Range	-45°C to + 100°C	
Soldering Condition	260°C For 10 Seconds	

Note:

1. 1/10DutyCycle,0.1msPulseWidth

Electrical Optical Characteristics Curves At Ta=25 °C

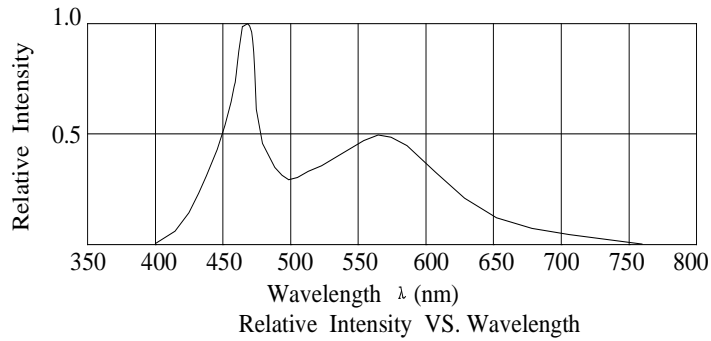


Fig.1 - Forward Voltage Shift vs. Junction Temperature

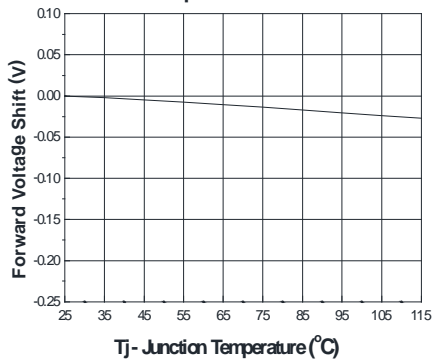


Fig.2 - Relative Luminous Intensity vs. Forward Current

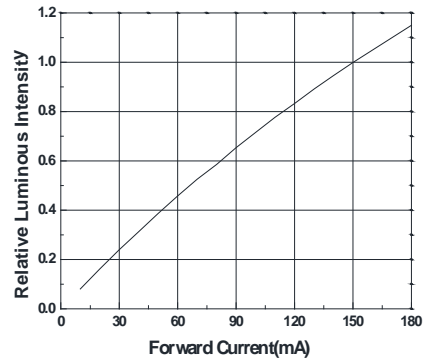


Fig.3 - Relative Luminous Intensity vs. Junction Temperature

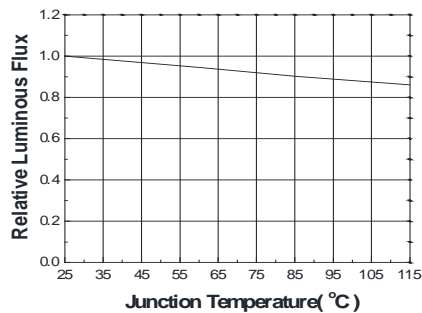


Fig.4 - Forward Current vs. Forward Voltage

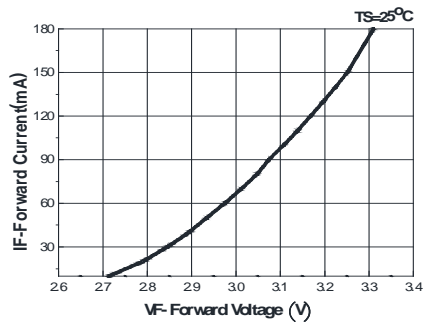


Fig.5 - Max. Driving Forward Current vs. Soldering Temperature

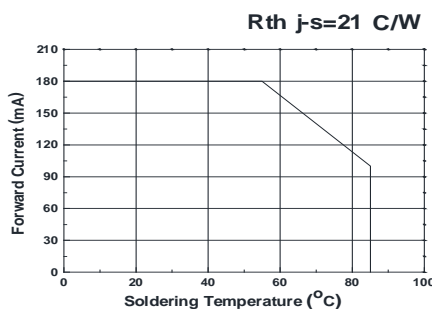
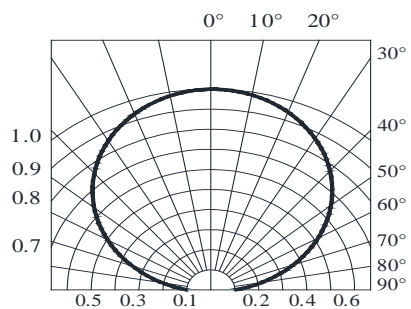


Fig.6 - Radiation Diagram





Bin Range Of Luminous Intensity (+/-15%)

Symbol	Bin Code	Min.	Max.	Unit	Condition
Iv	L30	30	35	lm	IF=120mA
	L35	35	40		
	L40	40	45		
	L45	45	50		
	L50	50	55		
	L55	55	60		
	L60	60	65		

Bin Range Of Forward Voltage (+/-0.1)

Symbol	Bin Code	Min.	Max.	Unit	Condition
VF	V25	2.5	2.7	V	IF=120mA
	V27	2.7	2.9		
	V29	2.9	3.1		
	V31	3.1	3.3		
	V33	3.3	3.5		



Chromaticity Coordinates Specifications for Bin Grading (+/-0.02)

6500k(IF=120mA)														
Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y
651	0.305	0.321	652	0.307	0.311	653	0.315	0.319	654	0.312	0.339	655	0.31	0.32
	0.303	0.33		0.305	0.321		0.314	0.324		0.321	0.348		0.308	0.33
	0.312	0.339		0.309	0.325		0.318	0.328		0.321	0.337		0.317	0.338
	0.312	0.334		0.31	0.32		0.317	0.333		0.317	0.333		0.318	0.328
	0.308	0.33		0.314	0.324		0.321	0.337		0.317	0.338			
	0.309	0.325		0.315	0.319		0.322	0.326		0.312	0.334			

5700k(IF=120mA)														
Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y
571	0.322	0.335	572	0.322	0.324	573	0.329	0.331	574	0.329	0.354	575	0.326	0.333
	0.321	0.346		0.322	0.335		0.329	0.336		0.338	0.362		0.325	0.344
	0.329	0.354		0.325	0.339		0.333	0.34		0.337	0.349		0.333	0.352
	0.329	0.348		0.326	0.333		0.333	0.346		0.333	0.346		0.333	0.34
	0.325	0.344		0.329	0.336		0.337	0.349		0.333	0.352			
	0.325	0.339		0.329	0.331		0.337	0.337		0.329	0.348			

5000k(IF=120mA)														
Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y
501	0.337	0.349	502	0.337	0.337	503	0.344	0.343	504	0.346	0.369	505	0.341	0.346
	0.338	0.362		0.337	0.349		0.345	0.349		0.355	0.376		0.342	0.359
	0.346	0.369		0.341	0.353		0.349	0.352		0.353	0.362		0.35	0.366
	0.346	0.362		0.341	0.346		0.349	0.359		0.349	0.359		0.349	0.352
	0.342	0.359		0.345	0.349		0.353	0.362		0.35	0.366			
	0.341	0.353		0.344	0.343		0.352	0.349		0.346	0.362			

4000k(IF=120mA)														
Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y
401	0.37	0.373	402	0.367	0.358	403	0.378	0.365	404	0.387	0.396	405	0.375	0.369
	0.374	0.387		0.37	0.373		0.381	0.373		0.401	0.404		0.378	0.384
	0.387	0.396		0.377	0.377		0.387	0.376		0.395	0.388		0.391	0.392
	0.385	0.388		0.375	0.369		0.389	0.384		0.389	0.384		0.387	0.376
	0.378	0.384		0.381	0.373		0.395	0.388		0.391	0.392			
	0.377	0.377		0.378	0.365		0.39	0.372		0.385	0.388			



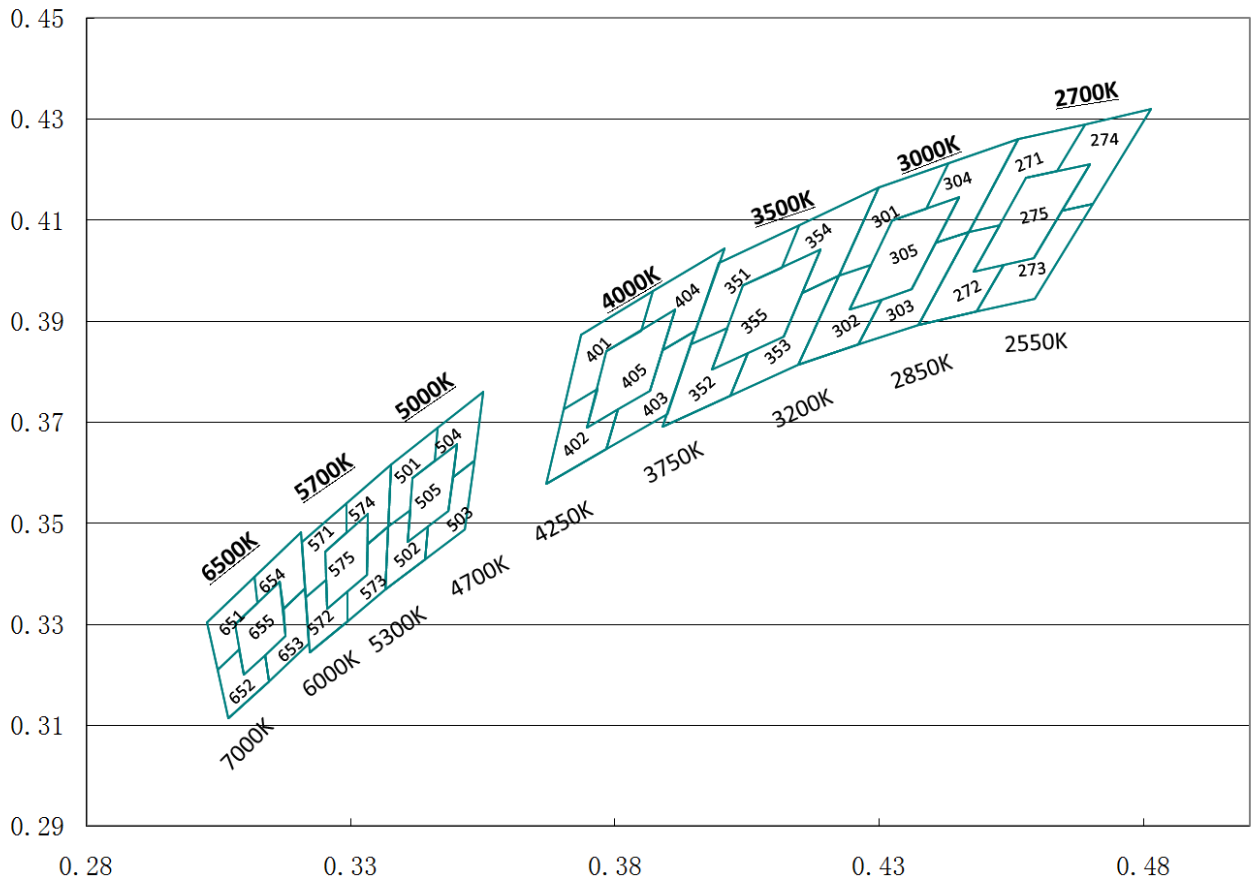
Chromaticity Coordinates Specifications for Bin Grading (+/-0.02)

3500k(IF=120mA)														
Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y
351	0.394	0.385	352	0.389	0.369	353	0.402	0.375	354	0.415	0.409	355	0.398	0.38
	0.4	0.402		0.394	0.385		0.405	0.384		0.43	0.417		0.404	0.397
	0.415	0.409		0.401	0.389		0.412	0.387		0.422	0.399		0.419	0.404
	0.412	0.401		0.398	0.38		0.415	0.396		0.415	0.396		0.412	0.387
	0.404	0.397		0.405	0.384		0.422	0.399		0.419	0.404			
	0.401	0.389		0.402	0.375		0.415	0.381		0.412	0.401			

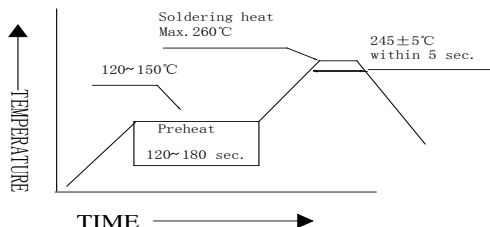
3000k(IF=120mA)														
Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y
301	0.422	0.399	302	0.415	0.381	303	0.426	0.385	304	0.443	0.421	305	0.424	0.392
	0.43	0.417		0.422	0.399		0.43	0.394		0.456	0.426		0.432	0.41
	0.443	0.421		0.428	0.401		0.4361	0.396		0.447	0.408		0.445	0.415
	0.439	0.412		0.424	0.392		0.441	0.406		0.441	0.406		0.436	0.396
	0.432	0.41		0.43	0.394		0.447	0.408		0.445	0.415			
	0.428	0.401		0.426	0.385		0.437	0.389		0.439	0.412			

2700k(IF=120mA)														
Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y	Rank	x	y
271	0.447	0.408	272	0.437	0.389	273	0.448	0.392	274	0.469	0.429	275	0.448	0.4
	0.456	0.426		0.447	0.408		0.453	0.401		0.481	0.432		0.458	0.418
	0.469	0.429		0.453	0.409		0.459	0.403		0.47	0.413		0.47	0.421
	0.464	0.42		0.448	0.4		0.464	0.412		0.464	0.412		0.459	0.403
	0.458	0.418		0.453	0.401		0.47	0.413		0.47	0.421			
	0.453	0.409		0.448	0.392		0.459	0.394		0.464	0.42			

CIE Chromaticity Diagram (+/-0.02)



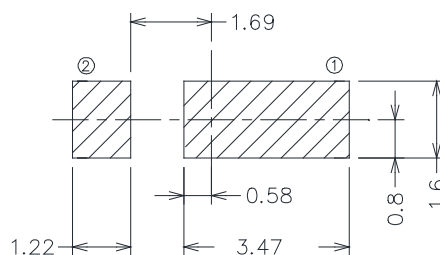
SMT Reflow Soldering Instructions



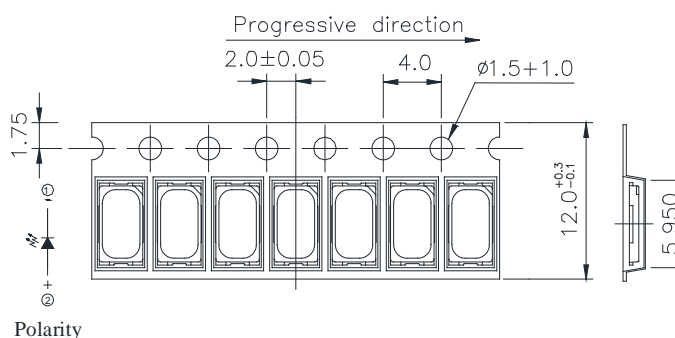
Notes:

1. Selles gives no other assurances regarding the ability of to withstand ESD. It is recommended to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.
2. Reflow soldering should not be done more than two times.
3. Do not stress LED when soldering, and do not warp the circuit board after soldering
4. While using Iron, Power dissipation of Iron should be smaller than 25W, and temperature should be controllable. The work should be finished within 2 sec under 320°C for once only.

Recommended Soldering Pad Dimensions



Package Specifications (Units: mm(inches))



Notes:

1. The LEDs should be used within a year.
2. The LEDs should be kept in 5~30°C and 60% RH for less.
3. The LEDs should be used within 24 hours, or else should be kept a 5~30°C and 30% RH or less. And LEDs should be used within 7 days after opening the package.

Reliability Test Items Conditions

Classification	Test Item	Test Conditions	Test hours	Result
Endurance Test	Operation Life	Connect with a power $I_F=120\text{mA}$ $T_a=\text{Under room temperature}$	1000Hrs	0/20
	High Temperature High Humidity	$T_a=+65^\circ\text{C}\pm 5^\circ\text{C}$ $RH=90\%-95\%$	240Hrs	0/20
	High Temperature Storage	High $T_a=+85^\circ\text{C}\pm 5^\circ\text{C}$	1000Hrs	0/20
	Low Temperature Storage	Low $T_a=-35^\circ\text{C}\pm 5^\circ\text{C}$ Test time=1000hrs	1000Hrs	0/20
Environmental Test	Temperature Cycling	$-45^\circ\text{C}\sim+105^\circ\text{C}$ 15min 5min 15min	300 Cycles	0/20
	Thermal Shock	$-35^\circ\text{C}\sim\pm 5^\circ\text{C}\sim+85^\circ\text{C}\sim\pm 5^\circ\text{C}$ 5min 10sec 5min	300 Cycles	0/20
	Solder Resistance	Preheating: $120^\circ\text{C}-150^\circ\text{C}$, within 2 minutes. Operation heating : 260°C (Max.), within 5 seconds (Max.)	5Cycles	0/20

Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	$V_F(\text{V})$	$I_F=120\text{mA}$	Over $U\times 1.2$
Reverse current	$I_R(\mu\text{A})$	$V_R=5\text{V}$	Over $U\times 2$
Luminous intensity	$I_v(\text{mcd})$	$I_F=120\text{mA}$	Below $S\times 0.5$

Note: 1.U means the upper limit of specified characteristics. S means initial value.

2.Measurment shall be taken between 2 hours after the test pieces have been returned to normal ambient conditions after completion of each test.